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(71) Applicant: **APPLIED MATERIALS, INC.** [US/US];
3050 Bowers Avenue, Santa Clara, California 95054 (US).

(72) Inventors: **BERNT, Marvin, L.**; 3050 Bowers Avenue,
Santa Clara, California 95054 (US). **BURNHAM, James,
C.**; 3050 Bowers Avenue, Santa Clara, California 95054
(US). **MIKKOLA, Robert**; 3050 Bowers Avenue, Santa
Clara, California 95054 (US).

(74) Agent: **MCCORMICK, Daniel, K.** et al.; 1100 Peachtree
Street NE, Suite 2800, Mailstop: IP Docketing - 22, Atlanta,
Georgia 30309 (US).

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(54) Title: ELECTROPLATING SEED LAYER BUILDUP AND REPAIR

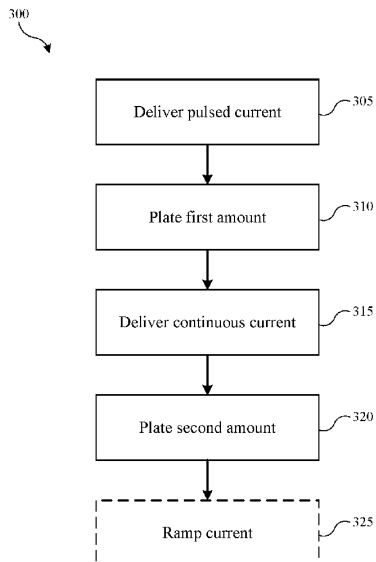


FIG. 3

(57) Abstract: Exemplary methods of electroplating may include delivering a current from a power supply through a plating bath of an electroplating chamber for a first period of time. The current delivered may be or include a pulsed current at a duty cycle of less than or about 50%. The methods may include plating a first amount of metal on a substrate within the plating bath. The substrate may define a via within the substrate. The methods may include, subsequent the first period of time, transitioning the power supply to a continuous DC current delivery for a second period of time. The methods may include plating a second amount of metal on the substrate.

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